

Patent Abstracts of Japan

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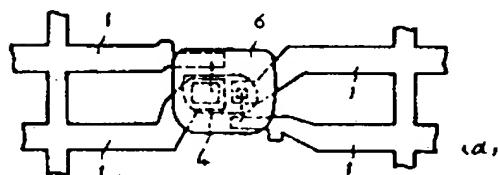
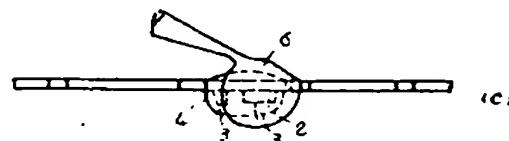
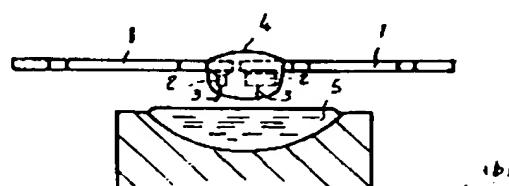
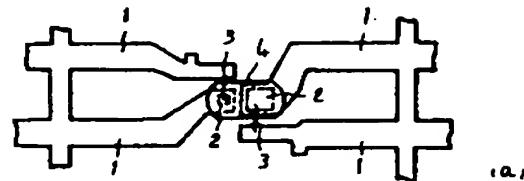
APPLICATION DATE : 14-07-83
APPLICATION NUMBER : 58128970

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TITLE : MANUFACTURE OF PHOTO COUPLER



ABSTRACT : PURPOSE: To achieve the molding with good reproducibility by immersing the element-side surface of a photo semiconductor in uncured resin after covering the photo semiconductor with the light transmitting resin and before molding with light reflecting resin.

CONSTITUTION: On the plural lead tongues 1, 1... of the lead frame consisting of copper, iron and etc. which are arranged separately with being close one another, the photo semiconductors 2 and 2 such as the light emitting diode consisting of GaAs and the phototransistor consisting of Si are placed on the same surface and wiring is made by use of the metal thin wires 3 and 3 such as gold and Al wires. Then, the both photo semiconductors 2 and 2 are coated with the light transmissive resin 4 such as Si resin. Next, the surface of the lead tongues 1, 1 on which the photosemiconductors 2 and 2 are placed is turned downward and is immersed in the uncured resin 5 and is then picked up. Subsequently, the light reflecting resin 6 such as the Si resin mixing a light reflecting agent is flowed from the surface where the photo semiconductors 2 and 2 do not exist. The light reflecting resin 6 flows downward and it shows the predetermined shape which covers at least the whole surface of the light transmissive resin 4 by surface tension. In this process, the part whose wetting properties becomes better adheres firmly.

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